SPECIFICATION AMENDMENTS

Replace the paragraph at page 1, lines 3-8 with the following paragraph:

This application is a continuation-in-part of U.S. Application Serial No. 10/235,331 (now U.S. Patent No. 6,653,742) filed September 5, 2002, which is a divisional of U.S. Application Serial No. 09/939,140 filed August 24, 2001(now U.S. Patent No. 6,576,539), which is a continuation-in-part of U.S. Application Serial No. 09/878,626 filed June 11, 2001(now U.S. Patent No. 6,653,217), which is a continuation-in-part of U.S. Application Serial No. 09/687,619 filed October 13, 2000 (now U.S. Patent No. 6,440,835), each of which is incorporated by reference.

Replace the paragraph at page 60, lines 9-15 with the following paragraph:

The through-holes can be formed using laser ablation (including laser direct write without a mask and projection laser ablation with a mask) or plasma etching. Similarly, the through-holes can be formed by a combination of laser ablation and plasma etching. See, for instance, U.S. Application Serial No. 10/302,642 filed November 23, 2002 (now U.S. Patent No. 6,699,780) by Cheng-Lien Chiang et al. entitled "Method of Connecting a Conductive Trace to a Semiconductor Chip Using Plasma Undercut Etching" which is incorporated by reference. In addition, the through-holes can be formed simultaneously or in sequence.

Replace the paragraph at page 62, line 20 to page 63, line 13 with the following paragraph:

The connection joint can be formed from a wide variety of materials including copper, gold, nickel, palladium, tin, alloys thereof, and combinations thereof, can be formed by a wide variety of processes including electroplating, electroless plating, ball bonding, solder reflowing, conductive adhesive curing, and welding, and can have a wide variety of shapes and sizes. The shape and composition of the connection joint depends on the composition of the routing line as well as design and reliability considerations. Further details regarding an electroplated connection joint are disclosed in U.S. Application Serial No. 09/865,367 filed May 24, 2001

(now U.S. Patent No. 6,562,709) by Charles W.C. Lin entitled "Semiconductor Chip Assembly with Simultaneously Electroplated Contact Terminal and Connection Joint" which is incorporated by reference. Further details regarding an electrolessly plated connection joint are disclosed in U.S. Application Serial No. 09/864,555 filed May 24, 2001 (now U.S. Patent No. 6,660,626) by Charles W.C. Lin entitled "Semiconductor Chip Assembly with Simultaneously Electrolessly Plated Contact Terminal and Connection Joint" which is incorporated by reference. Further details regarding a ball bond connection joint are disclosed in U.S. Application Serial No. 09/864,773 filed May 24, 2001 (now U.S. Patent No. 6,511,865) by Charles W.C. Lin entitled "Semiconductor Chip Assembly with Ball Bond Connection Joint" which is incorporated by reference. Further details regarding a solder or conductive adhesive connection joint are disclosed in U.S. Application Serial No. 09/927,216 filed August 10, 2001 (now U.S. Patent No. 6,548,393) by Charles W.C. Lin entitled "Semiconductor Chip Assembly with Hardened Connection Joint" which is incorporated by reference. Further details regarding a welded connection joint are disclosed in U.S. Application Serial No. 10/302,642 filed November 23, 2002 (now U.S. Patent No. 6,699,780) by Cheng-Lien Chiang et al. entitled "Method of Connecting a Conductive Trace to a Semiconductor Chip Using Plasma Undercut Etching" which is incorporated by reference.